



Material Content Data Sheet



Sales Product Name		TLE42994G		Issued		25. September 2017		
MA#		MA000970078						
Package		PG-DSO-8-16		Weight*		83.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.995	3.59	3.59	35902	35902
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8596	
wire	non noble metal	copper	7440-50-8	29.121	34.90	35.81	349040	358173
	noble metal	gold	7440-57-5	0.146	0.17	0.17	1746	1746
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1139
plastics		epoxy resin	-	4.371	5.24		52392	
	inorganic material	silicondioxide	60676-86-0	43.046	51.61	56.96	515946	569477
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9876	9876
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7794	7794
glue	plastics	acrylic resin	-	0.313	0.37		3747	
	noble metal	silver	7440-22-4	1.108	1.33	1.70	13285	17032
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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